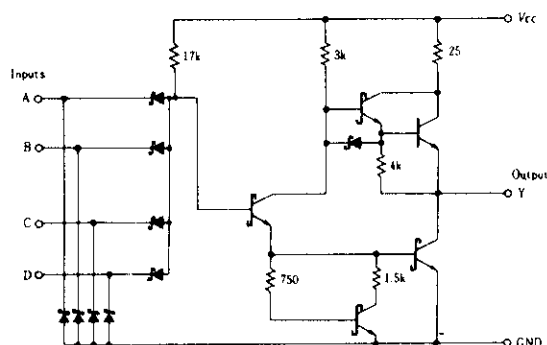
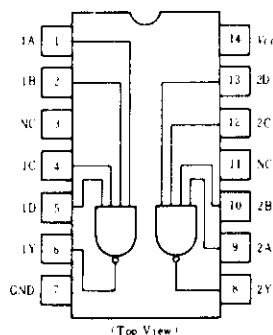


HD74LS40 ●Dual 4-input Positive NAND Buffers

■CIRCUIT SCHEMATIC(1/2)



■PIN ARRANGEMENT



■RECOMMENDED OPERATING CONDITIONS

Item	Symbol	min	typ	max	Unit
High level output current	I_{OH}	—	—	-1.2	mA
Low level output current	I_{OL}	—	—	24	mA

■ELECTRICAL CHARACTERISTICS ($T_a = -20 \sim +75^\circ\text{C}$)

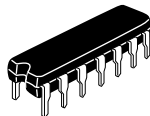
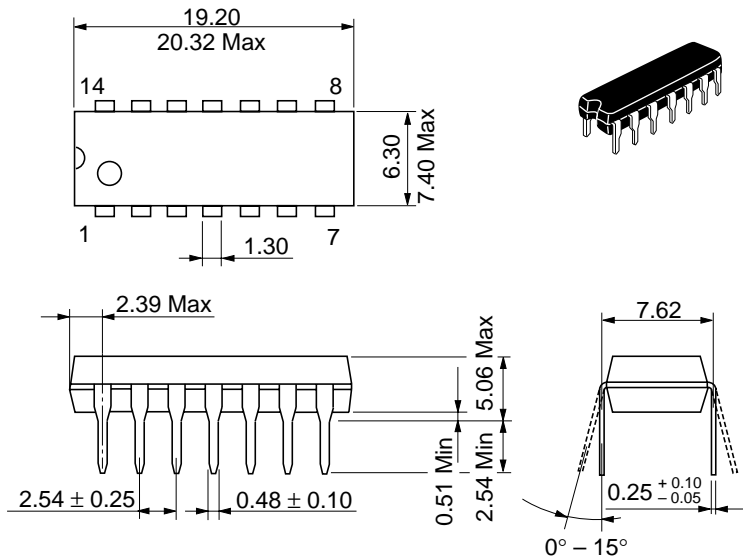
Item	Symbol	Test Conditions	min	typ*	max	Unit
Input voltage	V_{IH}		2.0	—	—	V
	V_{IL}		—	—	0.8	V
Output voltage	V_{OH}	$V_{CC}=4.75\text{V}$, $V_{IL}=0.8\text{V}$, $I_{OH}=-1.2\text{mA}$	2.7	—	—	V
	V_{OL}	$V_{CC}=4.75\text{V}$, $V_{IH}=2\text{V}$, $I_{OL}=24\text{mA}$	—	—	0.5	V
		$I_{OL}=12\text{mA}$	—	—	0.4	
Input current	I_{IH}	$V_{CC}=5.25\text{V}$, $V_i=2.7\text{V}$	—	—	20	μA
	I_{IL}	$V_{CC}=5.25\text{V}$, $V_i=0.4\text{V}$	—	—	-0.4	mA
	I_i	$V_{CC}=5.25\text{V}$, $V_i=7\text{V}$	—	—	0.1	mA
Short-circuit output current	I_{OS}	$V_{CC}=5.25\text{V}$	-30	—	-130	mA
Supply current	I_{CCH}	$V_{CC}=5.25\text{V}$	—	0.45	1.0	mA
	I_{CCL}	$V_{CC}=5.25\text{V}$	—	3	6	mA
Input clamp voltage	V_{IK}	$V_{CC}=4.75\text{V}$, $I_{IN}=-18\text{mA}$	—	—	-1.5	V

* $V_{CC}=5\text{V}$, $T_a=25^\circ\text{C}$

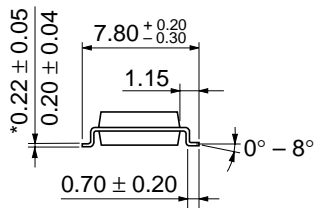
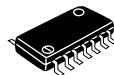
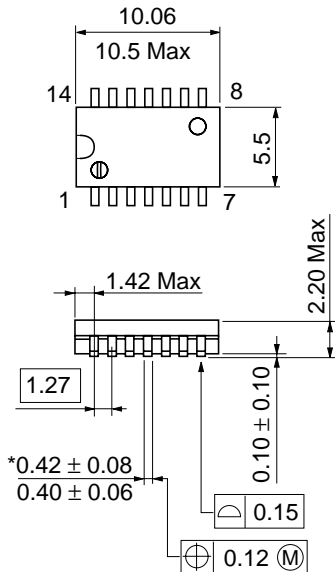
■SWITCHING CHARACTERISTICS ($V_{CC}=5\text{V}$, $T_a=25^\circ\text{C}$)

Item	Symbol	Test Conditions	min	typ	max	Unit
Propagation delay time	t_{PLH}	$C_L=45\text{pF}$, $R_L=667\Omega$	—	12	24	ns
	t_{PHL}		—	12	24	ns

Note) Refer to Test Circuit and Waveform of the Common Item

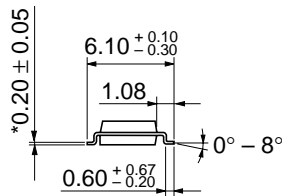
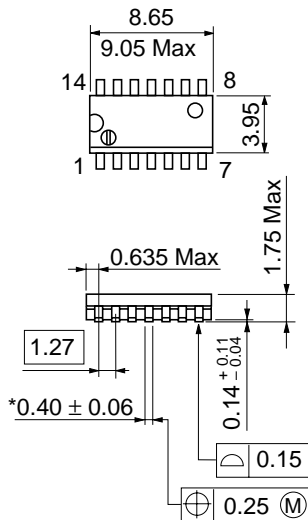


Hitachi Code	DP-14
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.97 g



Hitachi Code	FP-14DA
JEDEC	—
EIAJ	Conforms
Weight (reference value)	0.23 g

*Dimension including the plating thickness
Base material dimension



Hitachi Code	FP-14DN
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.13 g

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HITACHI

Hitachi, Ltd.

Semiconductor & Integrated Circuits.
Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan
Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

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For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose, CA 95134 Tel: <1> (408) 433-1990 Fax: <1> (408) 433-0223	Hitachi Europe GmbH Electronic components Group Dornacher Straße 3 D-85622 Feldkirchen, Munich Germany Tel: <49> (89) 9 9180-0 Fax: <49> (89) 9 29 30 00 Hitachi Europe Ltd. Electronic Components Group. Whitebrook Park Lower Cookham Road Maidenhead Berkshire SL6 8YA, United Kingdom Tel: <44> (1628) 585000 Fax: <44> (1628) 778322
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Hitachi Asia Pte. Ltd.
16 Collyer Quay #20-00
Hitachi Tower
Singapore 049318
Tel: 535-2100
Fax: 535-1533

Hitachi Asia Ltd.
Taipei Branch Office
3F, Hung Kuo Building, No.167,
Tun-Hwa North Road, Taipei (105)
Tel: <886> (2) 2718-3666
Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd.
Group III (Electronic Components)
7/F., North Tower, World Finance Centre,
Harbour City, Canton Road, Tsim Sha Tsui,
Kowloon, Hong Kong
Tel: <852> (2) 735 9218
Fax: <852> (2) 730 0281
Telex: 40815 HITEC HX

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